



# Boschman Technologies

**Boschman Technologies is an experienced and dynamic hightech company serving the global semiconductor assembly industry providing quality solutions for high end packaging needs.**

Boschman Technologies is founded in 1990 and a technology leader in the field of manufacturing hightech auto molding and Ag-Sintering processes and systems for the semiconductor and electronics industry. Strategic market segments:

- Smartcards and discrete packages
- MEMS and sensor packages
- Power modules for electrical vehicles

## Mold\tools

All our mold\tools are developed, engineered, manufactured and tested at our mold tooling center in the Netherlands, all under one roof. Our design specialists and experienced craftsmen form a formidable team with one goal in mind: meeting your requirements.

## Molding and Sintering Systems

Our molding and sintering systems are developed at our systems R&D facility in the Netherlands. Mechanical, electrical, software, process and mold-design experts work in multi-disciplinary teams to realize the best possible total system solution. Systems are fully produced at Boschman Technologies Asia in Singapore.

## Customer involvement

We regularly join forces with R&D departments of our customers to co-develop and research innovative packaging concepts. Early involvement in the development process is a prerequisite to obtain the highest quality, reliable molding processes, the lowest cost of ownership and the shortest time to market. Local Service and sales teams present.



**Frank Boschman**  
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Boschman技术公司是一家行业经验丰富而充满活力的高科技公司，为全球半导体产业高端封装需求提供解决方案。

Boschman技术公司成立于1990年，为半导体及电子产业提供领先的高科技自动模封工艺及银烧结工艺和系统。

Boschman的战略市场包括：

- 智能卡和分立器件封装
- MEMS和传感器封装
- 电动汽车的功率模组封装

## 模具

我们所有的模具都在我们荷兰的模具加工中心全部自己开发、工程设计和生产。我们的设计师和经验丰富的技术工人组成了一个和谐团队，他们心中有一个共同的目标：满足您的技术要求。

## 模封和烧结系统

我们的塑封和烧结系统在我们位于荷兰的系统研发设施中开发。机械、电气、软件、工艺和模具设计的专家组成跨专业的技术队伍，以实现最优的整体解决方案。整机生产在位于新加坡的 Boschman技术亚洲有限公司。

## 客户参与

我们经常与客户的研发部门联合，共同开发或研究创新的封装形式。在开发新工艺中提前参与是获得高质量、高可靠性、低成本的模封工艺，缩短进入市场周期的前提条件。Boschman在全球设有本地化的技术售后服务和销售队伍。



## Contact

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